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Andt  
J. McNeill  
9/11/02

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TECHNOLOGY CENTER 2800

DATE: September 6, 2002

TO: U.S. Patent and Trademark Office -- Group Art Unit 2827  
Attention: Examiner T. Blum

FROM: W. Kevin Ransom

\* \* \* **OFFICIAL** \* \* \*

In re: Slemmons et al.  
Appl. No.: 10/005,633  
Filed: December 5, 2001  
For: MICROBEAM ASSEMBLY  
FOR INTEGRATED CIRCUIT  
INTERCONNECTION TO SUBSTRATES

Confirmation No.: 9245  
Group Art Unit: 2827  
Examiner: D. Gaybill

NO. OF PAGES:  
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Attorney's Docket No. 038190/241788

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

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Commissioner for Patents  
Washington, DC 20231

AMENDMENT

TECHNOLOGY CENTER 2800

Sir:

In response to the Office Action mailed June 6, 2002, please amend the above-identified application as follows:

In The Claims:

Please cancel claims 29 and 33 and amend Claims 25, 26, and 30 as follows:

25. A microbeam assembly adapted to form interconnects between integrated circuit bond pads and substrate contacts, the microbeam assembly comprising:

a carrier;

a plurality of conductive microbeams releasably bonded to the carrier, wherein the conductive microbeams are sized and spaced to mate with the bond pads of an integrated circuit, and wherein at least one of said conductive microbeams comprises solder coating a portion thereof;

a solder dam positioned on a surface of said at least one conductive microbeam comprising solder opposite said carrier, said solder dam for preventing solder from wetting along a portion of said microbeam not coated with solder; and

a release layer positioned between said carrier and said conductive microbeams for releasably supporting the conductive microbeams.